

35997 U.S. PTO
10/087556

03/01/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10087556	FILING DATE 03/01/2002	CLASS 257	SUBCLASS	GAU 2811	EXAMINER <i>lem</i>
**APPLICANTS: Yamaguchi Katsumi; Okazaki Tomohiro;					
**CONTINUING DATA VERIFIED: none Jmz					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2001-061381 03/06/2001 Jmz					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials Jmz		TI-31471			
TITLE : Semiconductor device and bump formation method					

U.S. DEPT. OF COMM./PAT. & TM-PTO-436 (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner		CLAIMS ALLOWED	
				Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner		DRAWING	
Amount Due	Date Paid			Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE		Application Examiner	
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